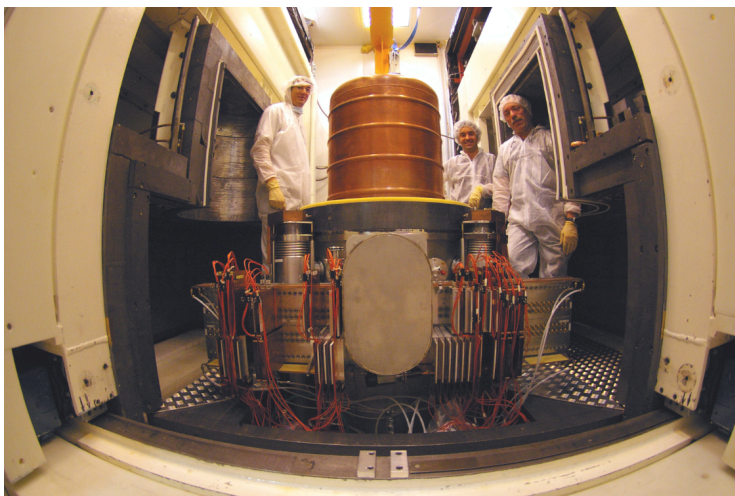
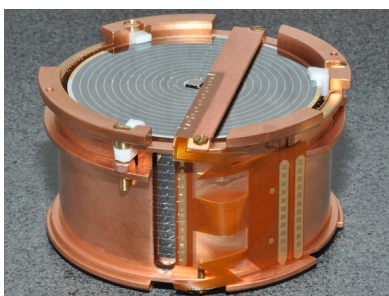


EDELWEISS-III progress report



*The project
Evolution of the scientific context
Progress report
Calendar, people and budget*

J. Gascon
UCB Lyon 1, CNRS/IN2P3/IPNL

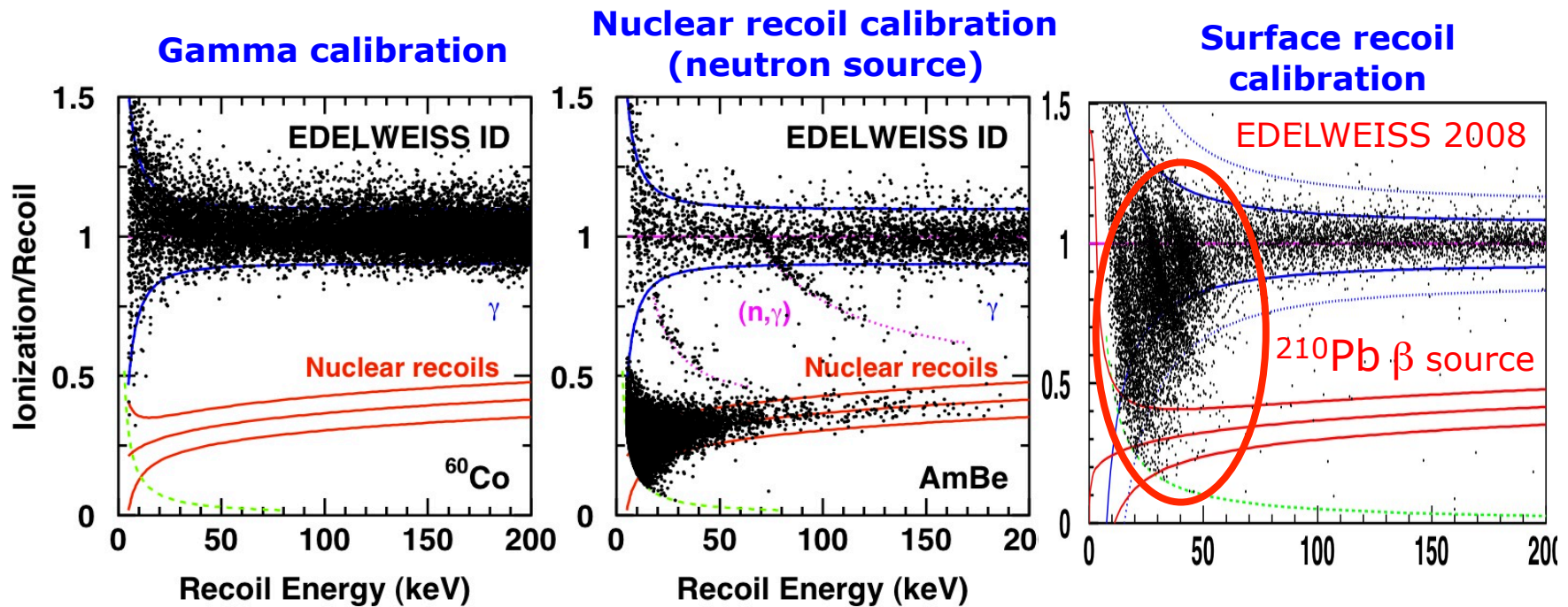
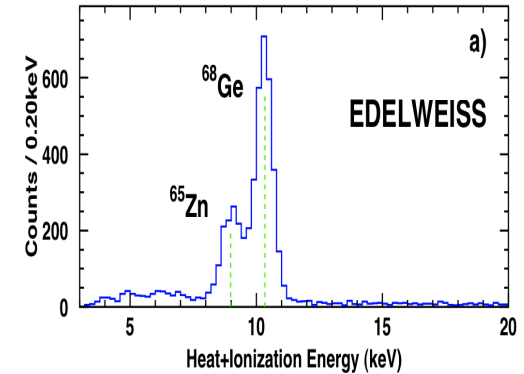
THE EDELWEISS-III PROJECT

The EDELWEISS collaboration objectives

- *Exploit the advantages of germanium cryogenic detectors for Direct Dark Matter searches*
 - Germanium radiopurity
 - Superior energy resolution on both heat and ionization channels:
 - Distinct, event-by-event discrimination between nuclear electron recoils using ionization yield relative to heat signal
 - Low thresholds
 - Precise spectroscopy of any remaining backgrounds
- *Obtain significant limits on WIMP with spin-independent interactions*
- *Develop a simple and robust detector unit that keeps all the advantages and can be adapted to larger scale project*
 - Recognized expertise for heat-and-ionization detector design, fabrication and for understanding the physics of these device.

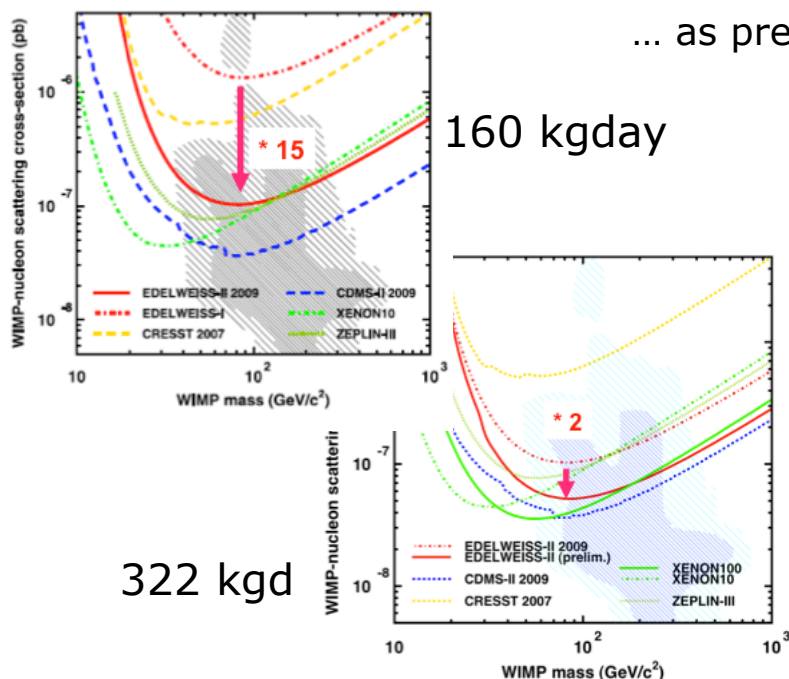
Germanium heat+ionization principle

- Heat = true calorimetric measurement of recoil energy (independent of slowing-down process)
- Sub-keV resolution for ionization and heat signals
- Ion. yield for nuclear recoils $\sim 1/3$ of e^- recoils
- *Limitation: charge collection near surface => different rejection strategy for CDMS & EDELWEISS*



Motivation for the EDELWEISS-III project (1)

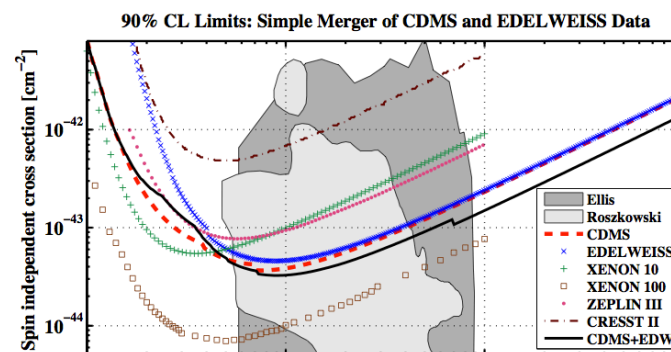
... as presented to the July 2010 IN2P3 Scientific Council



- With 10 x 400 g detectors (1.6 total fiducial mass) of the newly developed "ID" design, EDELWEISS improves x30 its previous background suppression performance and catches up with CDMS in terms of sensitivity
- *First direct proof that "ID" electrode design can efficiently remove background from surface events*

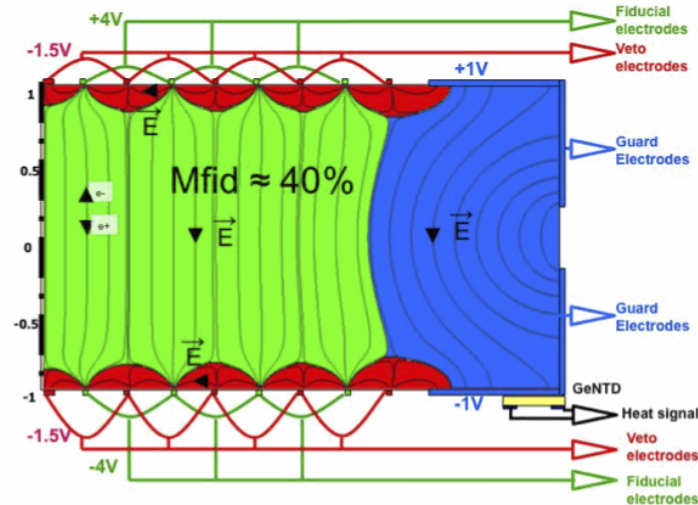
Update since 2010:

- Publication of final exposure (384 kgd)
- Combination with CDMS (379 kgd), improves best limits by x1.5 at high mass: joint paper
- *CDMS decides on an ID-inspired design for the electrodes of all its future detectors.*



Surface event rejection with ID electrodes

Φ 70mm, H 20mm, 410g
14 concentric electrodes
width 100 μ m, spacing 2mm



- Interleaved electrodes + guards
- Biases to have an electric field
~ horizontal near the surface and
~ vertical in the bulk

→ Easy cuts on « veto » + guard electrodes define the fiducial zone

Improved understanding of detector physics

Surface event selection:

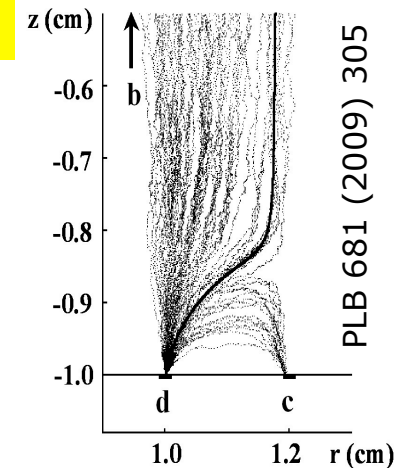
- First criteria: absence of signal on "veto" rings
- **Redundancy:** requires equality between "fiducial" rings on both sides

"Grid effect":

- High-field region close to fiducial electrodes improves charge collection in the region that needs it the most (surface)

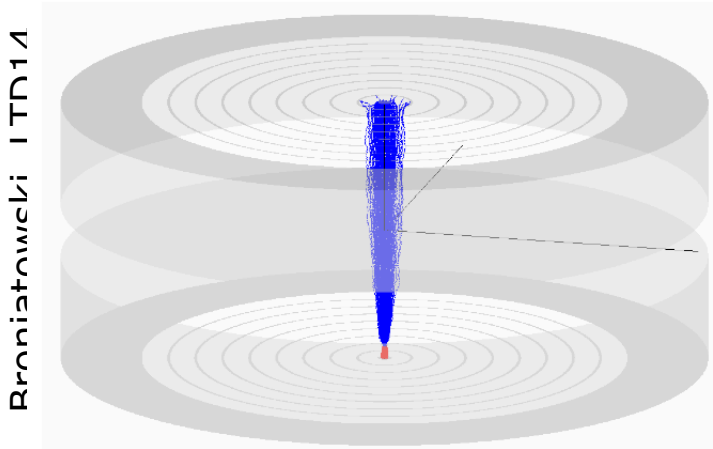
Charge transport effects:

- Diffusion (T=20mK) and charge repulsion removes problems that could have arisen from low-field regions



Charge transport in cryogenic germanium

a) Simulation includes impurity scattering but neglects electron transport anisotropy



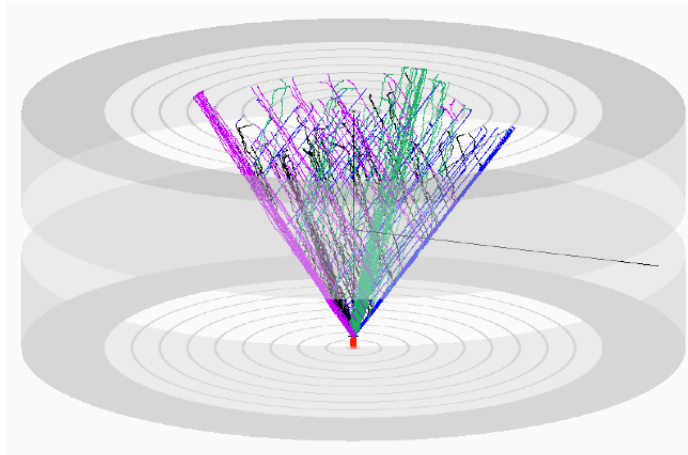
ID203
Height 20 mm
Diam. 50 mm
Ge p-type
doped to
 10^{11} cm^{-3}
Field: 0.5V/cm

5

ID203: $N_{\text{scatt}} = 1.5 \times 10^{10} \text{ cm}^{-3}$, $V_a = 1\text{V}$.

LTD14 Heidelberg, Germany Aug. 1-5, 2011

c) Simulation treats the combined effects of impurity scattering and electron transport anisotropy

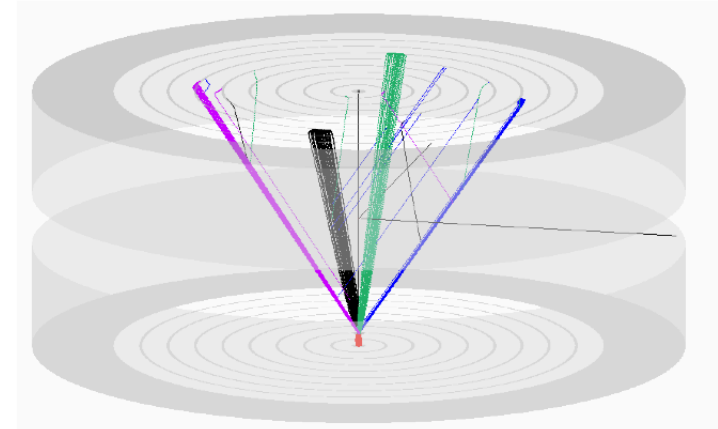


7

ID203: $N_{\text{scatt}} = 1.5 \times 10^{10} \text{ cm}^{-3}$, $V_a = 1\text{V}$.

LTD14 Heidelberg, Germany Aug. 1-5, 2011

b) Simulation treats electron transport anisotropy, but neglects impurity scattering



6

ID203: $N_{\text{scatt}} = 0$, $V_a = 1\text{V}$.

LTD14 Heidelberg, Germany Aug. 1-5, 2011

Since 2010:

Better understanding of detector physics

Confirmation of the benefit of covering all detector surfaces with ID electrodes

Reduction of backgrounds (1)

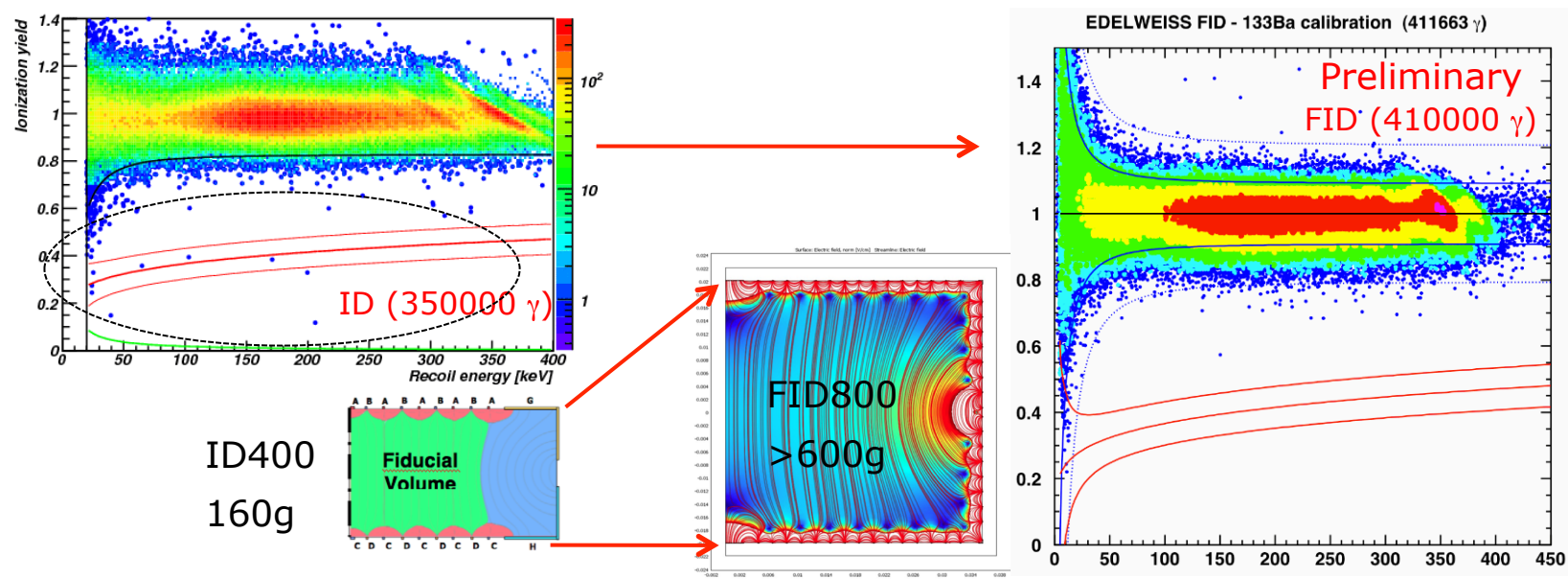
Good understanding of the limiting backgrounds in EDELWEISS-II

■ Gamma-ray background (~ 1 bkg event in EDWII)

Compton with part in the guard region (low field + poor charge collection)

- Improve rejection with detector fully covered with interleaved electrodes
 - Reduction of non-fiducial volume from 60% to 20%
 - Better charge collection for surface events due to grid effect

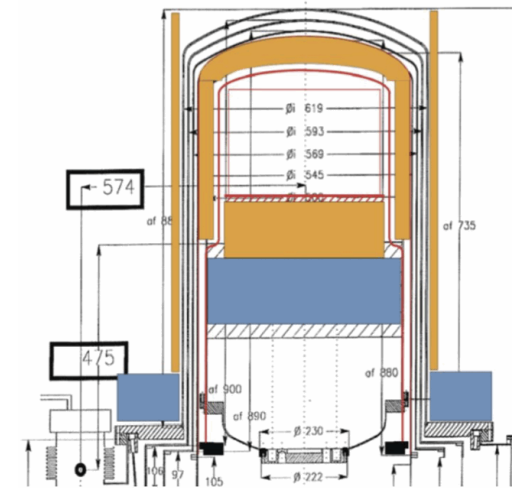
Since 2010: rejection improvement observed in FID800 γ calibrations



Reduction of backgrounds (2)

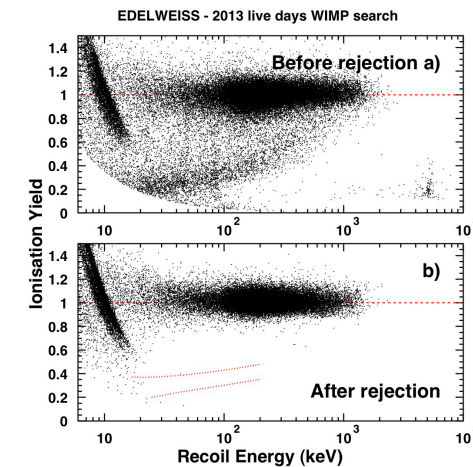
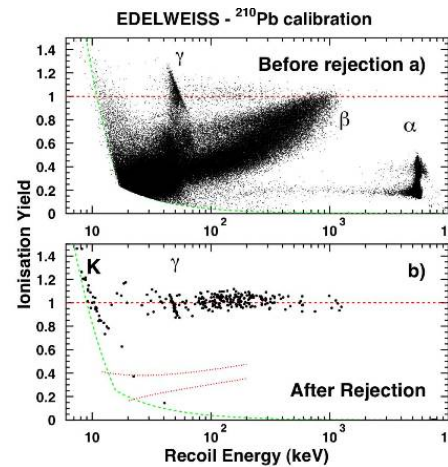
Good understanding of the limiting backgrounds in EDELWEISS-II

- Neutron background (~ 3 events in EDWII)
 - alpha-n reaction in material inside polyethylene shield
 - better material selection
 - ~ 10 cm internal polyethylene shield



Surface events background
(< 0.2 events in EDWII)

- Material selection
- Improved ionization resolution



FIDSUSY proposal (2010)

- Science goal: have a Ge array able to get 3000 kgd (with <1 bkg event) in 6 months ($=5 \times 10^{-9}$ pb)
- **40 x FID800 [ANR]** can do this (... as early as 2012):
 - X4 fiducial mass/detector wrt EDWII ID
 - Surface rejection of ID already ok
 - Need to improve on the γ -rejection wrt EDWII: has been confirmed in 2011 Run15
 - Need x10 improvement in neutron rejection: **internal shield**
- Assumed 20 keV_NR "sharp" threshold (reminder: EDW-II was 20 keV at the time)
 - Need improved/more reliable **cabling, electronics** (ionization resolutions >1 keV not acceptable) and **cryogenics** (main source of noise / deadtime due to excessive heat noise)

EDELWEISS-III collaboration and tasks



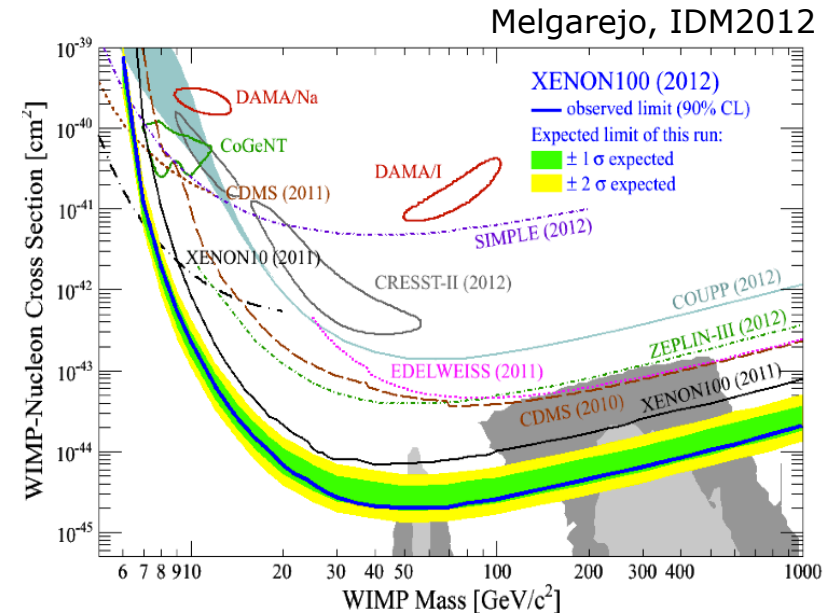
- Spokesman: *J. Gascon* (IPNL)
- Technical coordination: *A. Juillard* (IPNL)
- Relations with EURECA and CDMS: *G. Gerbier* (IRFU)

Task	Coordinators
<i>Cryogenics</i>	A. Benoit (Neel)
<i>Detectors</i>	S. Marnieros (CSNSM), X.F. Navick (IRFU)
<i>Cryogenic cabling</i>	A. Juillard (IPNL), H. Kraus (Oxford)
<i>Electronics & DAQ</i>	B. Paul + M. Gros (IRFU), M. Kleifges (IPE)
<i>Low radioactivity and shielding</i>	V. Kudryavtsev (Sheffield)
<i>Muon veto and ancillary detectors</i>	K. Eitel (IK), E. Yakushev (Dubna)
<i>Offline and Monitoring</i>	E. Armengaud (IRFU), J. Gascon (IPNL)
<i>Database and documentation</i>	A. Cox + V. Kozlov (IK)

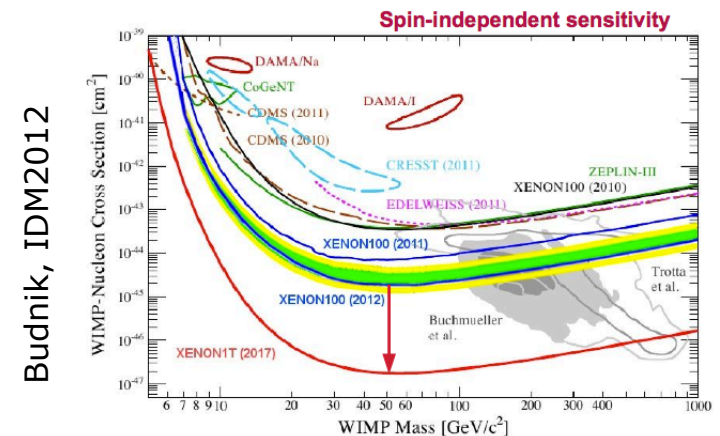
EVOLUTION OF THE SCIENTIFIC CONTEXT

XENON-100 results

- 224 days
- 38 kg fiducial mass
- 2 observed events
(predicted: 1)
- New limits: 2×10^{-9} pb
at $M_{\text{WIMP}} = 50$ GeV

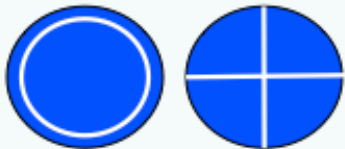

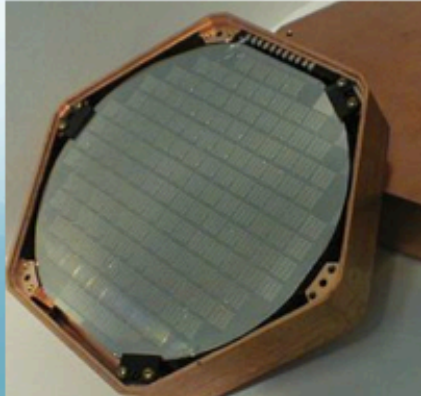
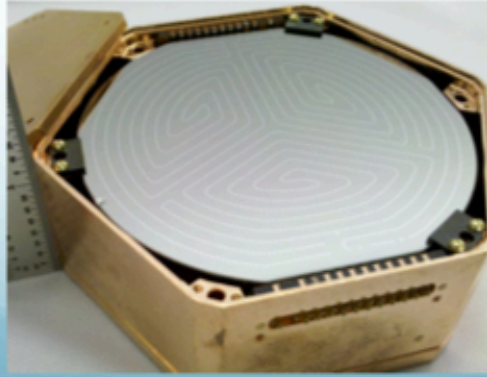


- XENON 1t construction started
- 2400 kg Xe (XENON100 x 15)
- Data taking to start in 2015
- With x100 background reduction,
goal of 2×10^{-11} pb in 2017.



SuperCDMS Soudan: 650g iZIPs

- Phonon timing + phonon symmetry + ID electrodes (*but no veto electrode readout*)
- 9 kg (6 kg fiducial)
- Data started in 2012, **2200 kgd by 2014**
 6×10^{-9} pb for 100 GeV/c²
- Goals of low thresholds for low-mass WIMPs
(at the expense of surface event rejection from phonon timing)


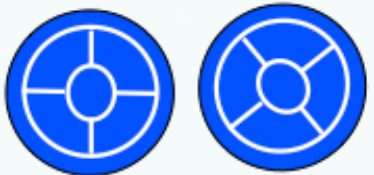
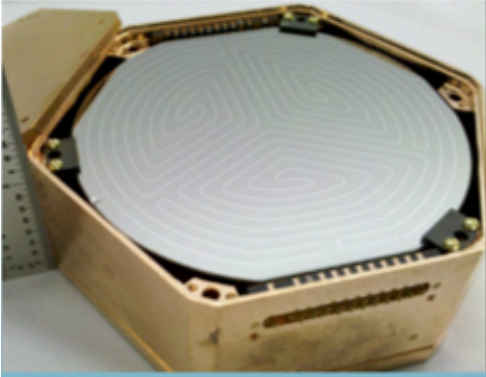
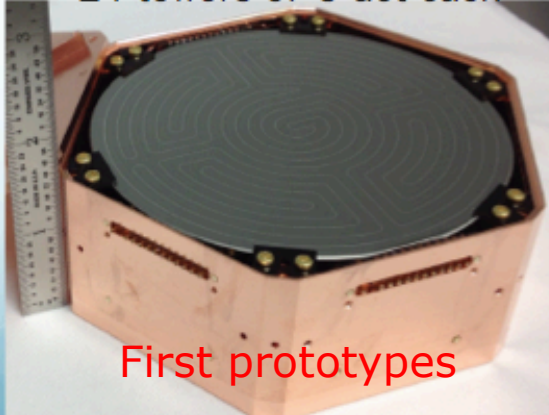
CDMS II	SuperCDMS Soudan
Single-sided 1 cm thick 3" diameter 250 g Ge	Double-sided 2.5 cm thick 3" diameter 620 g Ge
2 charge + 4 phonon	2 charge + 2 charge 4 phonon + 4 phonon
	
5 towers of 6 det each	5 towers of 3 det each
	

Cushman, IDM2012

Future Project: SuperCDMS at SNOLAB

- 1.38 kg iZIPs
- R&D to be completed in 2013
- Goal: 200 kg Ge
140 000 kgd
(4 year run)
 10^{-10} pb in ~ 2017

*~EURECA
time scale*

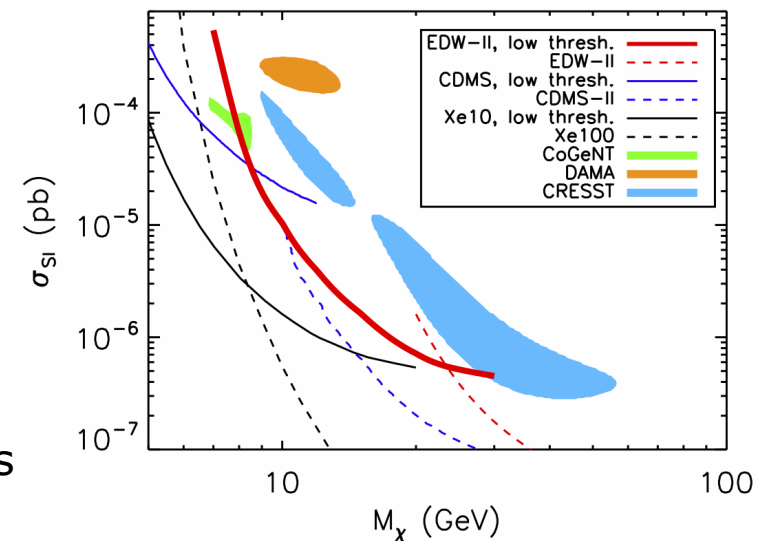
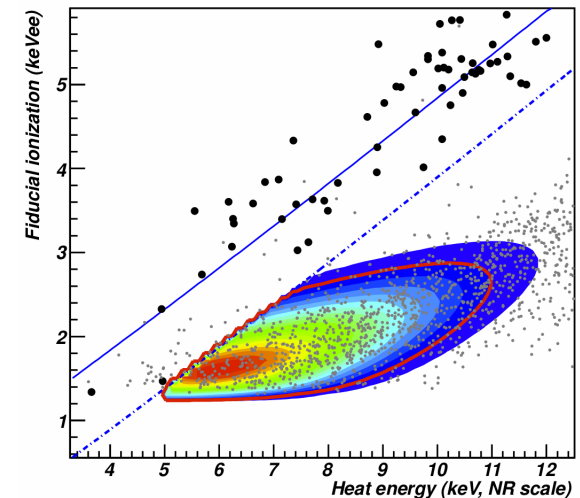
SuperCDMS Soudan	SuperCDMS SNOLAB
<div style="border: 1px solid black; padding: 5px; width: fit-content;"> Double-sided 2.5 cm thick 3" diameter 620 g Ge </div>	<div style="border: 1px solid black; padding: 5px; width: fit-content;"> Double-sided 3.3 cm thick 4" diameter 1.38 kg Ge </div>
7.5 cm	10 cm
2 charge + 2 charge 4 phonon + 4 phonon	2 charge + 2 charge 6 phonon + 6 phonon
	
Running	
5 towers of 3 det each	24 towers of 6 det each
	
	First prototypes

Cushman, IDM2012

Recent EDELWEISS low mass analysis

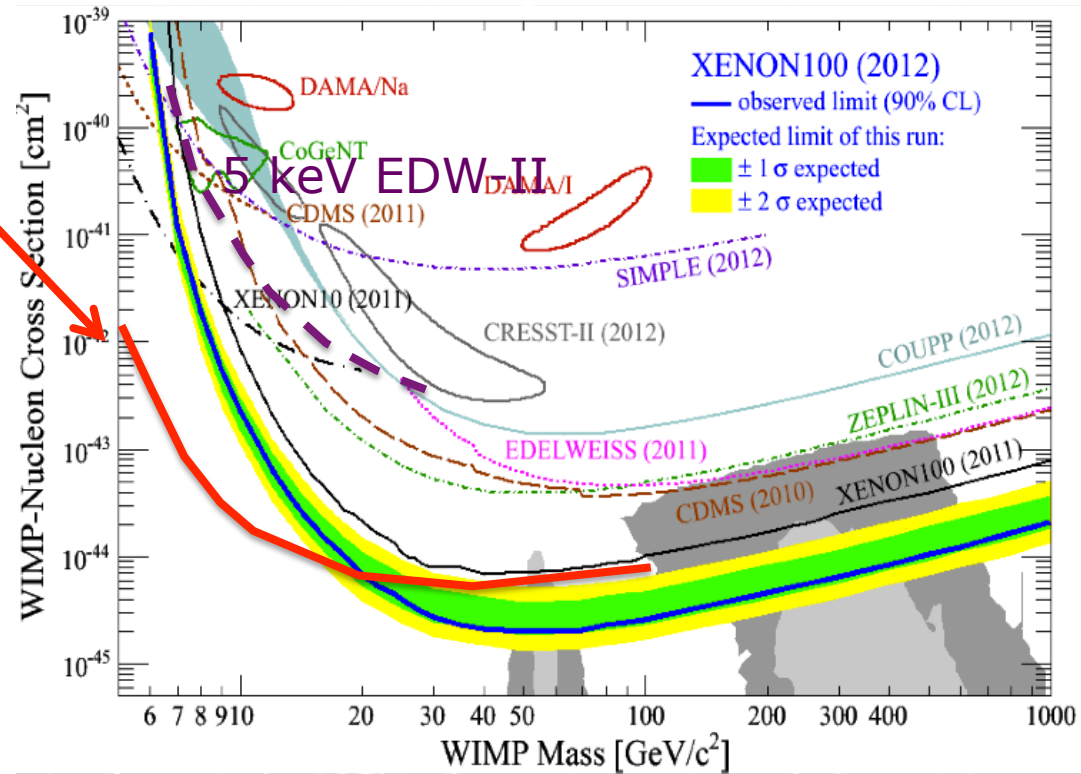
PRD 86 (2012) 051701R

- Realization that, despite being tuned for $M_{\text{WIMP}} \sim 100$ GeV, EDELWEISS-II had significant efficiency down to 5 keV recoil
- *Significant background rejection with ID electrodes down to low energy: EDELWEISS-ID limit better than CDMS in 8-10 GeV range*
- Resolutions are improving with new electronics (900 eV \rightarrow 650 eV for ionization, 1.25 \rightarrow <1 keV for heat)
- 500 eV achieved in tests (HEMT R&D to go down to 300 eV?)
- EDW-III will have more aggressive goals concerning thresholds



Motivation for low thresholds

- Coverage of low-mass region with 4 FID detectors with 300 eV FWHM resolutions (1200 kgd)

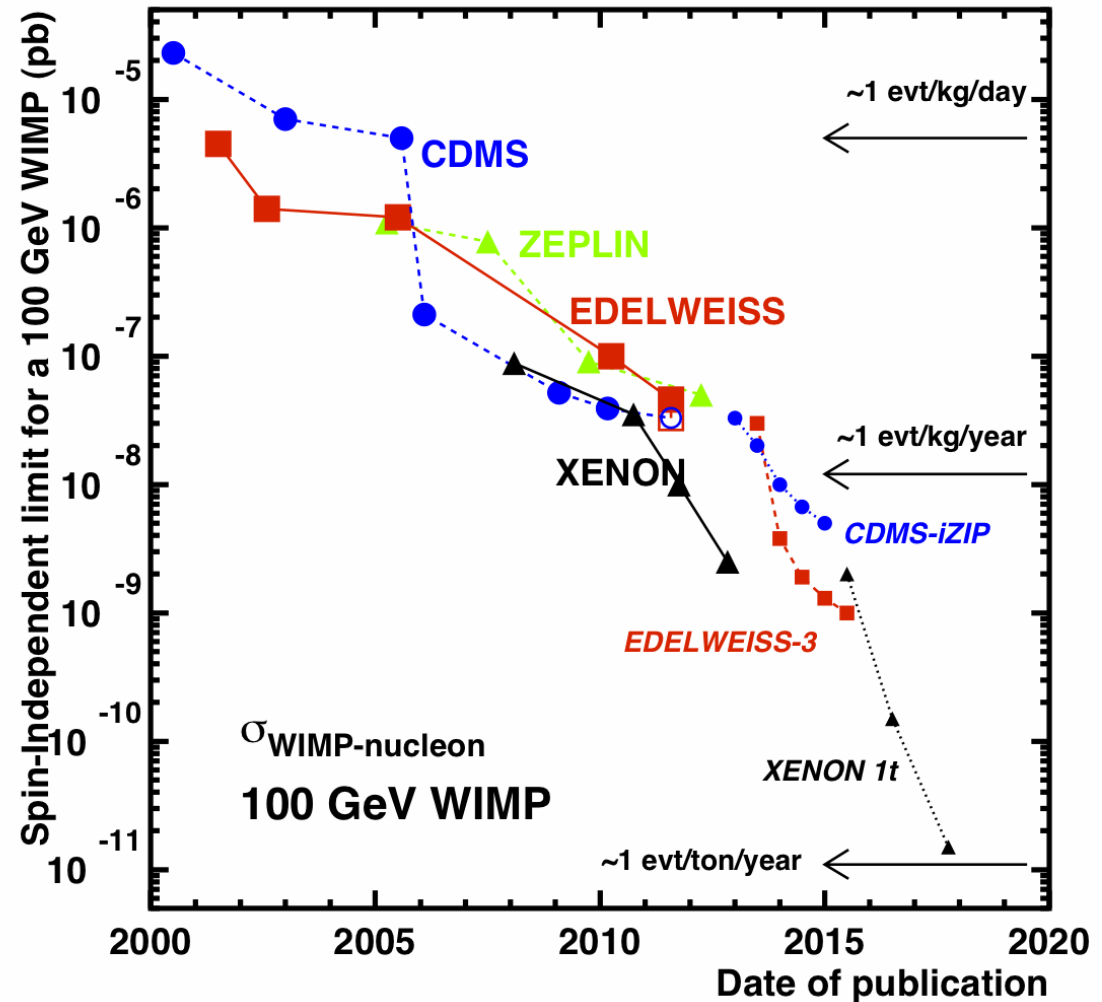


EDELWEISS-III Objectives Update

- One year late (mainly: leakage current problem discussed later)
- Slope of 3000 kgd / 6 month should be reached mid-2013
- Achieved improvements in resolution show that an average 10 keV threshold is possible, with significant efficiency down and little backgrounds down to 5 keV
 - Improves sensitivity for 3000 kgd to $3-4 \times 10^{-9}$ pb instead of 5×10^{-9} pb
 - 3 keV thresholds on a few R&D detectors is possible (HEMT)
- Range of background from internal neutrons limits total exposure to 4500 kgd (2.5×10^{-9} pb at 15 keV) to 12000 kgd (10^{-9} pb at 15 keV)
- *Depending on backgrounds, EDELWEISS-III could reach 1 to 2.5×10^{-9} pb before the start of XENON-1t and SuperCDMS SNOLAB*

- Need to address low mass WIMPs
 - Recent paper: better than CDMS at 8-10 GeV/c^2
 - ~ 5 keV threshold already possible with good IDs
 - significant surface event rejection with cut on veto signals

Present limits vs CDMS/EDW3 predictions



PROGRESS REPORT

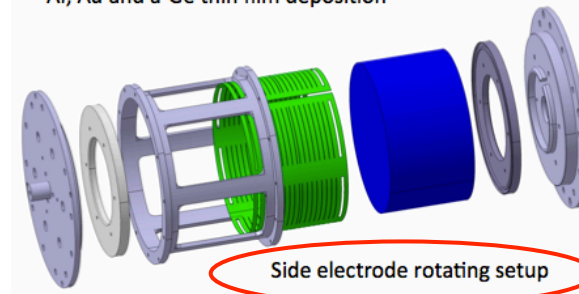
EDELWEISS electron-beam evaporator (CSNSM)

FID detector processing

- 810 g Ge crystals are received already polished & etched
 - 10 Canberra + 24 BSI received
 - Additional 10 BSI purchased
- α -Ge underlayer deposition
- Al electrodes & contact pads deposition
- Au heat link pads deposition
- Ion beam cleaning (Ar) prior to each deposition
- Mask positioning outside the evaporator
- Ge-NTD heat sensor gluing
- Process shortened to 2.5 day by using same mask for α -Ge and Al
- *Planning based on 1 FID / week*

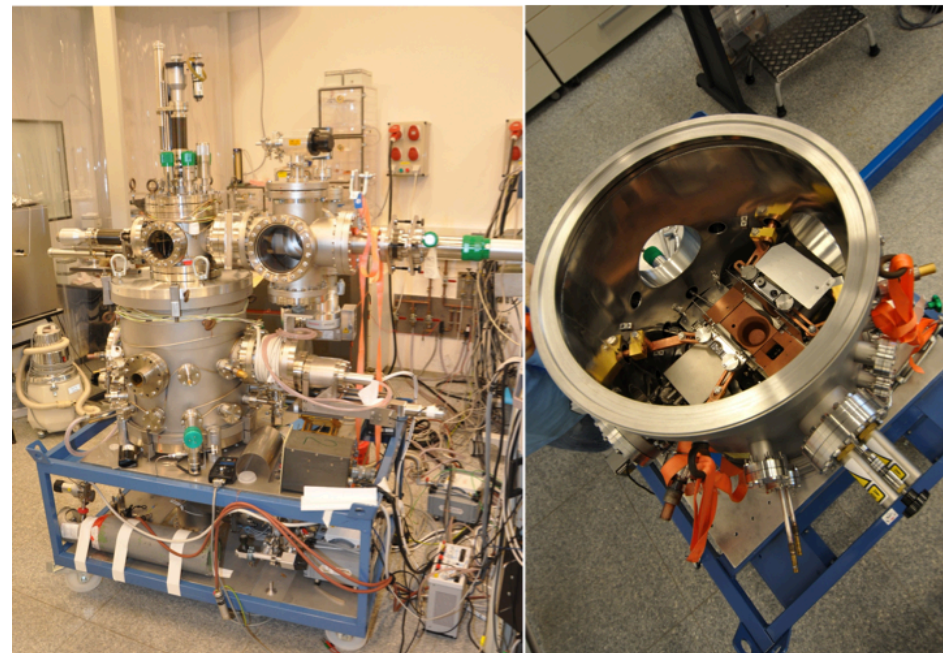
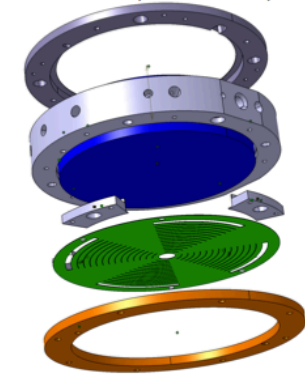
e-beam evaporator & shadow masks

Al, Au and α -Ge thin film deposition



Not readily available industrially

Face evaporation setup



FID production

- Challenge wrt to ID: lateral evaporation
- First 3 FID800 could handle $\pm 4V$ polarizations with no leakage current ($\ll 1$ fA)
- Production of next 10 FIDs: all but the second one suffer from leakage between adjacent electrodes, on either curved or flat surfaces or both.
- Intensive study to understand the origin of this problem, and to find a solution
- One year delay in detector production

Leakage current: solution

Need a solution that keeps the simplicity of the process, is ~100% efficient and ideally can be used to repair detectors *after* the leakage diagnostic

- Several detector processing alternatives have been tested:
 - *Electrodes under-layer material (H- α Ge, α Ge, SiO, no under-layer)*
 - *Ion-beam cleaning optimization*
 - *Ammonium sulfide surface passivation*
 - *Chemical etching (selective etch of Ge relative to Au and Al)* [CSNSM bolometer matrices R&D]
- After these studies and consulting experts (including CDMS, facing similar problems): problem most probably related to surface defects of Ge between Al electrodes, possibly linked to the initial mechanical polishing and chemical etching.

The selected chemical etching procedure *after the detector fabrication* is 100% efficient in removing leakage currents problems (11/11 detector treated)

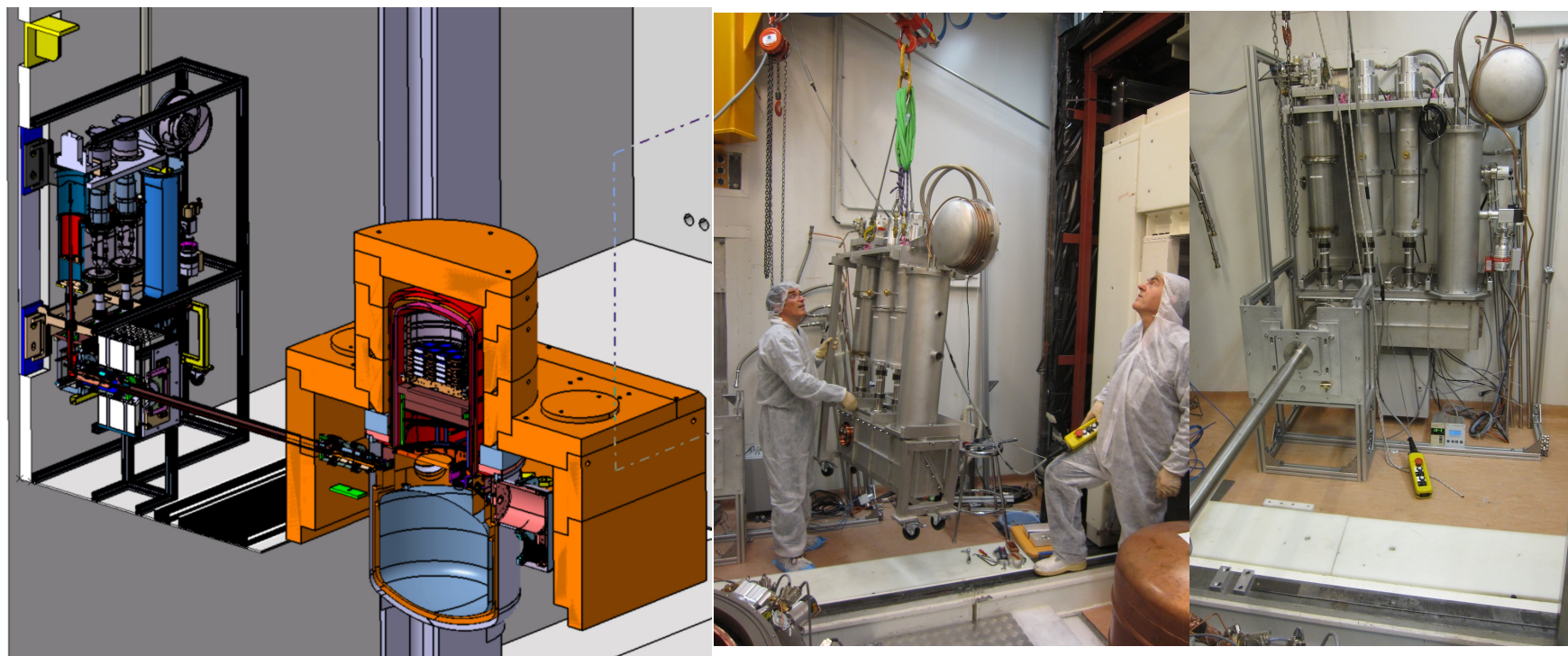
- A procedure has been optimized: it can be applied to the entire past production (without ungluing the NTD sensors) and preserves FID performances
- Actual procedure to be the object of a publication next year

2011-2012 calendar (1)

- 2011: Runs in Modane to help understand the leakage problems, and to study the performance of the three working FID800
 - Very good reproducibility
 - Fiducial volume conforms expectations
 - Improved gamma rejection than ID over entire fiducial volume
 - Better charge collection in non-fiducial regions than ID
- End 2011: Test new electronics, cabling and new NTD sensors
 - Baseline resolutions on fiducial ionization improves from ~ 1 keV (in EDELWEISS-II ID) to 0.65 keV FWHM
- Spring/Summer 2012: Upgrade of cryogenics
 - Lower and more consistent microphonics noise level to obtain a more homogeneous data sample with < 1 keV heat resolution

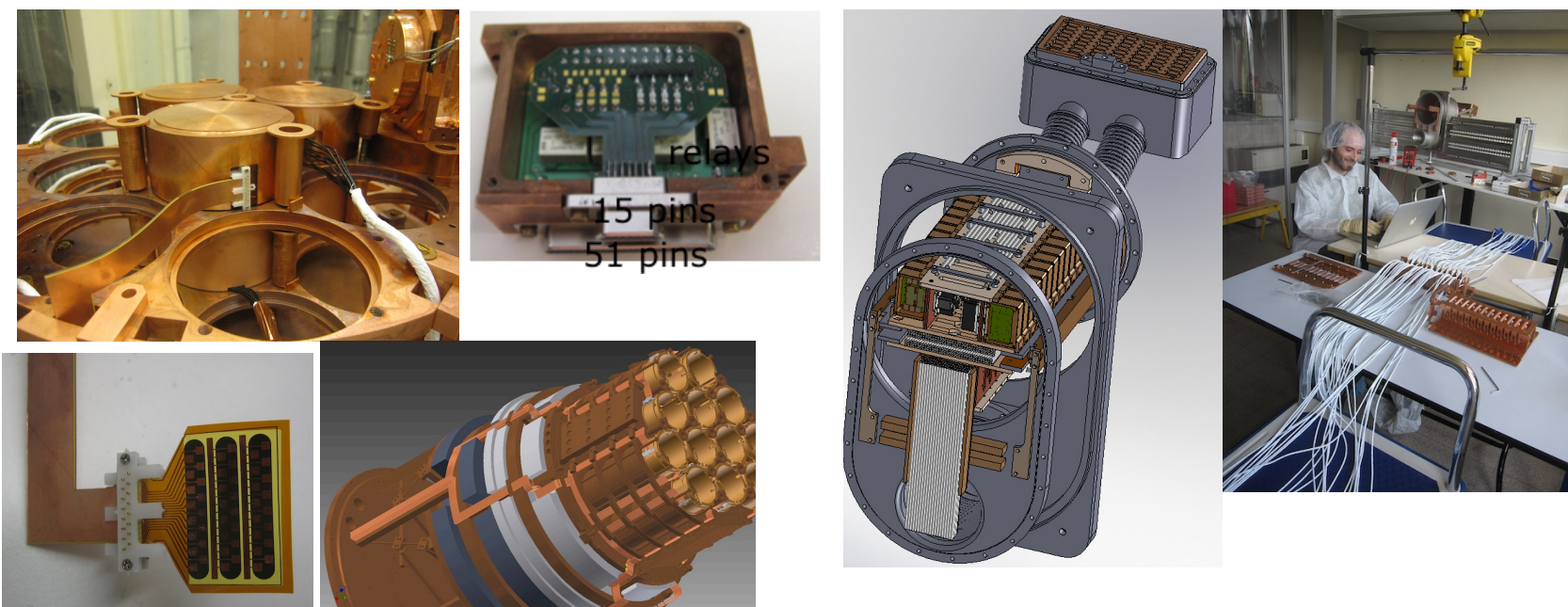
New Cryogenics machines

- Objective: move “noisy” pulse-tube out of inner shields
- Replace with thermal machines on LSM wall
- Cold transported via fluids in caloduc



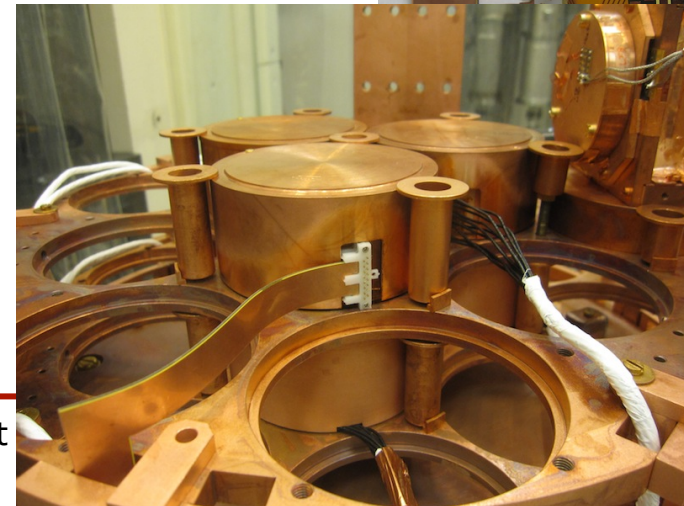
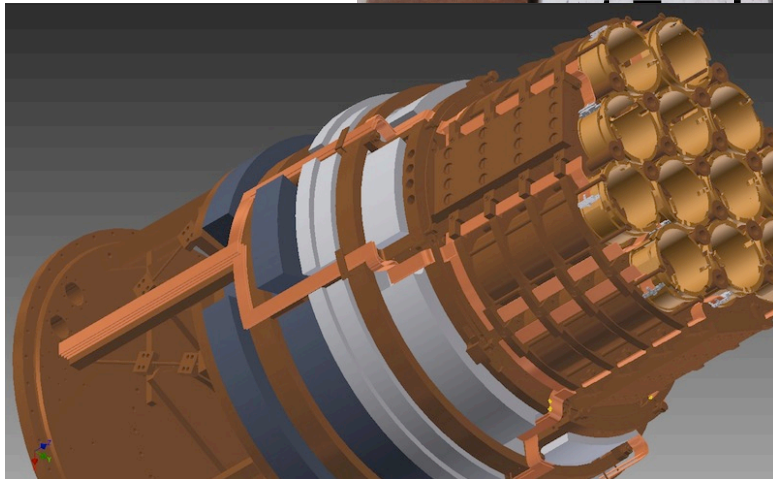
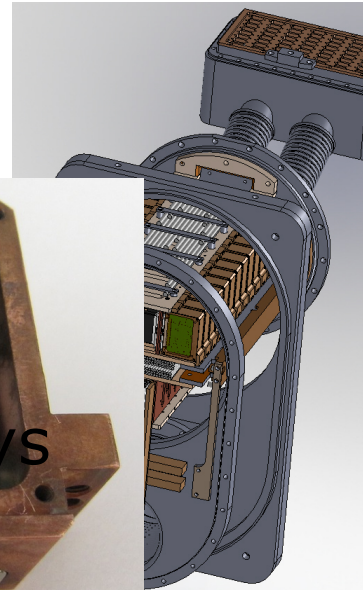
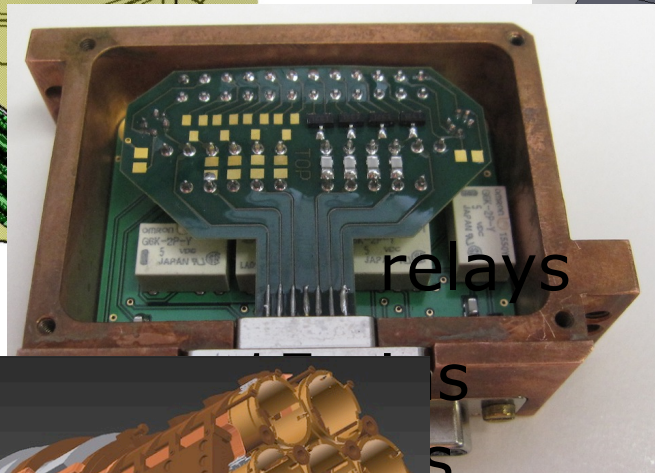
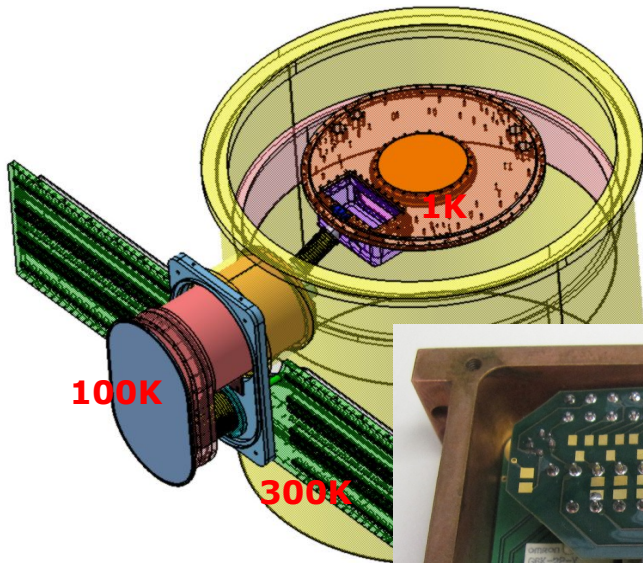
2011-2012 calendar (2)

- Autumn 2012: Test of new Cu screens adapted to new PE shield
- Test of new kapton for 10-100 mK connection
- Preparation in IPNL of cabling for full detector array



- Also at LSM: test of ZnMo detectors (A. Giuliani, ANR LUMINEU)

Cryogenic cabling status



Calendar for the coming years

- Run 20 (started october 2012): 6 FIDs
 - Final confirmation of performance of detectors with new surface treatment (done)
 - High-statistics beta calibration of FID800
- Start now final production of FIDs (1/week)
- Installation of new cabling and shields in December
- Run with 15 FIDs starting January 2013
 - Commissioning, large-statistics gamma calibration
- Run with 40 in summer 2013
- First 3000 kgd in winter 2013 (3000 kgd per 6 months)
- >10 000 kgd before end 2015

PEOPLE AND BUDGET

Edelweiss-III project: Budget

- We're within budget
- Savings on detector helped electronics + shields
- Investments spending 92% completed in 2012.

	2010 projection	Budget 2010-2013	2013 part	ANR part	in2p3 part
Detectors +NTDs	900 kE	810 kE	0	694 kE	0
Cryogenics	100 kE	138 kE	0	0	50
Electronics + cabling	330 kE	387 kE	110 kE	146 kE	30
Shields	30 kE	139 kE	0	0	0
Operations*	150 kE/y	112 kE/y	145 kE	0	~60 kE/y
4-year Total	2070 kE	1921 kE	255 kE	840 kE	330 kE

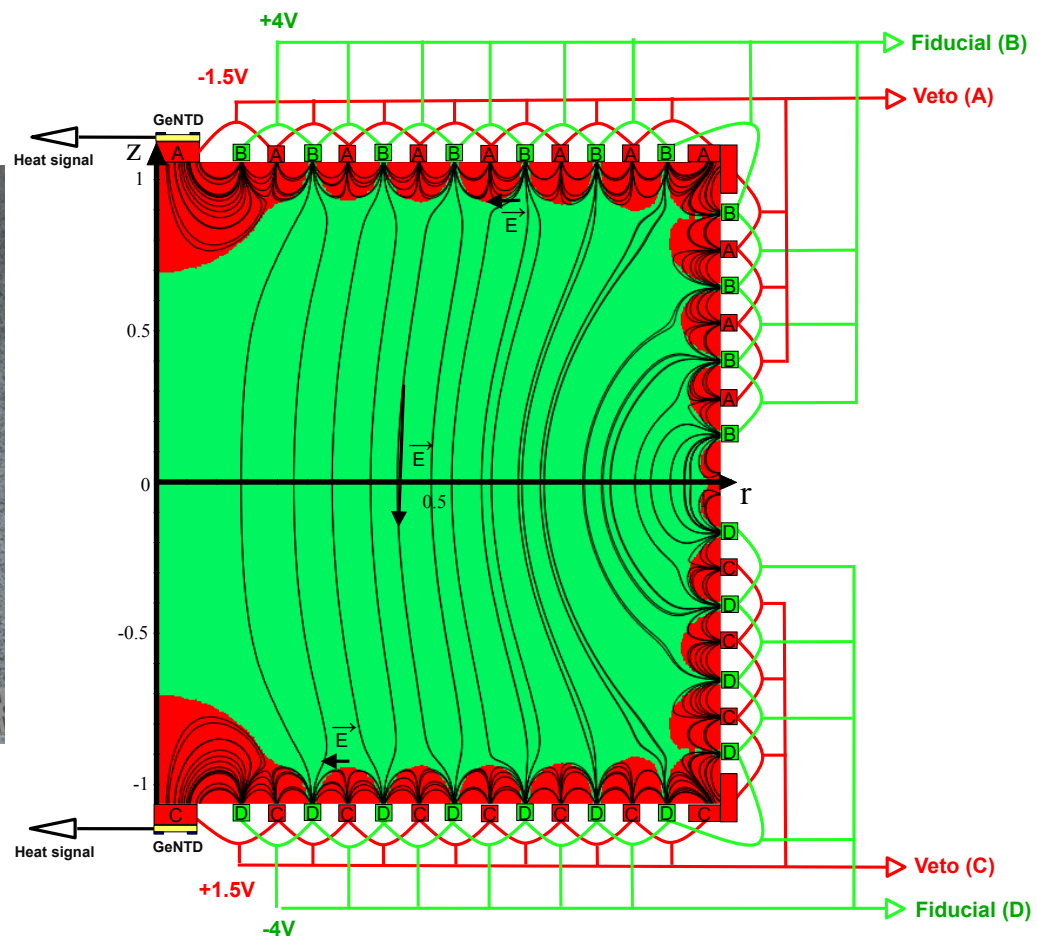
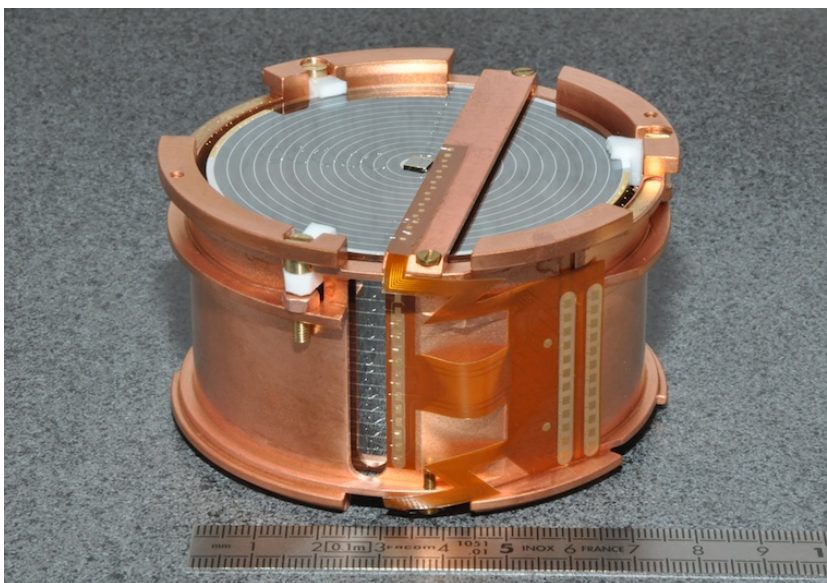
* Costs of operations in LSM. Do not include travels (~40 kE/y for in2p3) and operations and R&D in in2p3 labs (~45 kE/y)

- More people than ever...
 - New group on DAQ electronics (IPE-Karlsruhe)
 - Excellent integration of recent members: IPE, and also Oxford (since 2010, cryogenic cabling) and Sheffield (since 2011, radioactive background and simulations)
 - 3 Postdocs (1 Paris, 2 KIT) + ...
 - 8 PhD (4.5 KIT, 1.5 Lyon, 1 Paris, 1 Oxford) + ...
 - 2 Diploma + ...
 - Since 2011, +2 permanents in IPNL, +1.5 in CSNSM, +1 in CEA, ...

Conclusion

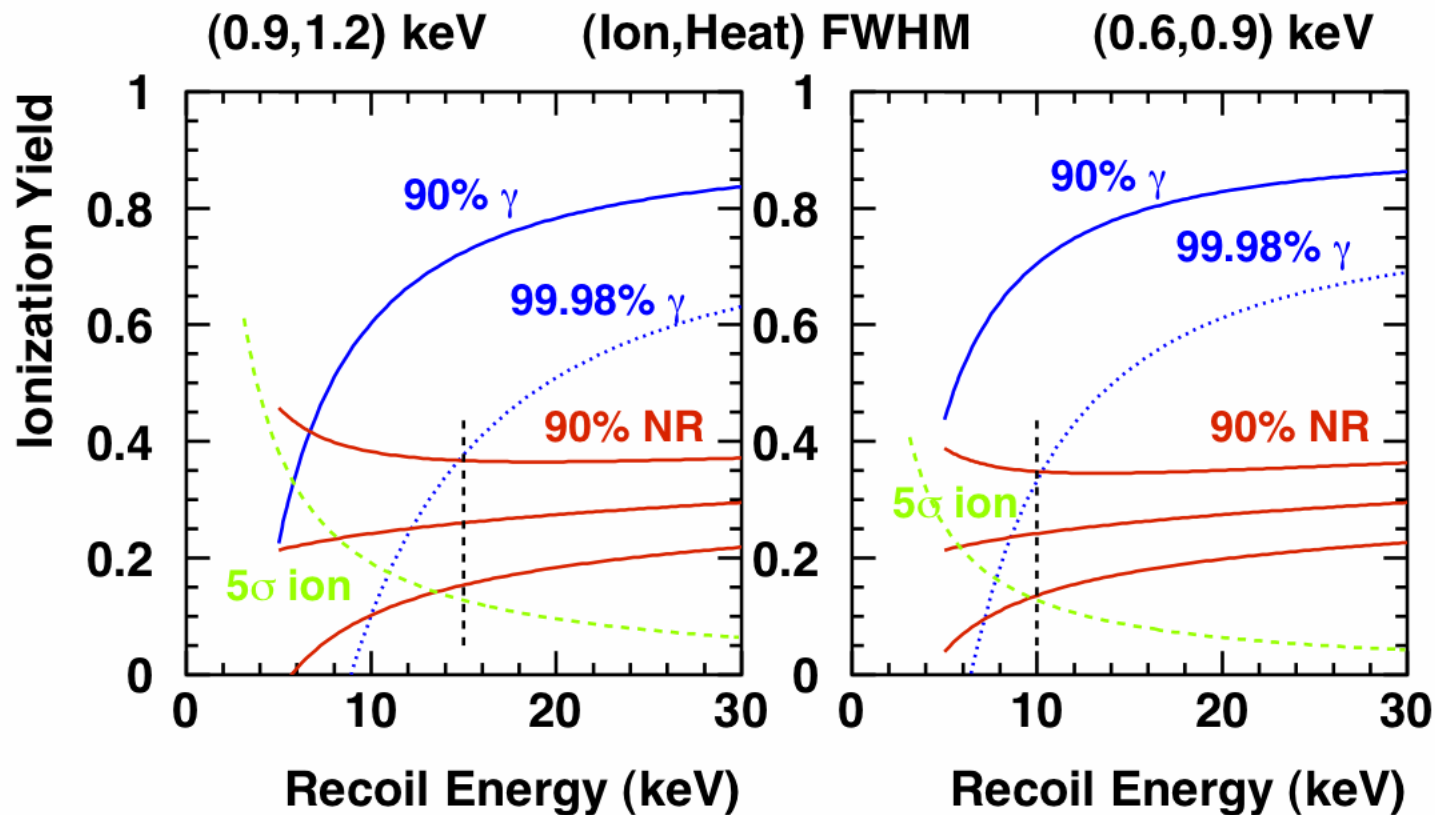
- After a year delay solving leakage current problems, detector production can now resume
- The delay was used to progress on the upgrade of the environment (cryogenics, cabling, electronics, shielding)
 - New electronics and cryogenics have resulted in >30% improvements in resolutions with respect to EDELWEISS-II. The average threshold should move down from 20 to 10 keV, with significant efficiency down to 5 keV or less.
- The goal of 3000 kgd/ 6 month will be reached in 2013
- Background level estimates allow for a two year run, resulting in a sensitivity of $>1 \times 10^{-9}$ pb
 - Establish our simple & reliable FID technology as the best starting point for future large-scale cryogenics Ge projects, in Europe or with American partners

EDELWEISS FID detectors



Recoil thresholds

- EDW-II *average* FWHM keV: 0.9 Ion + 1.2 Heat
- (worse EDWII: 1.5 keV + 2 to 3 keV)

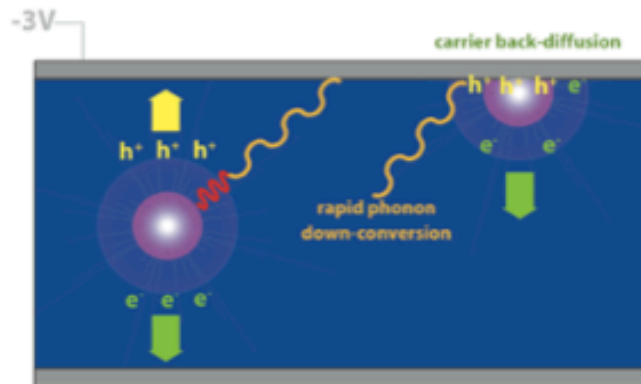
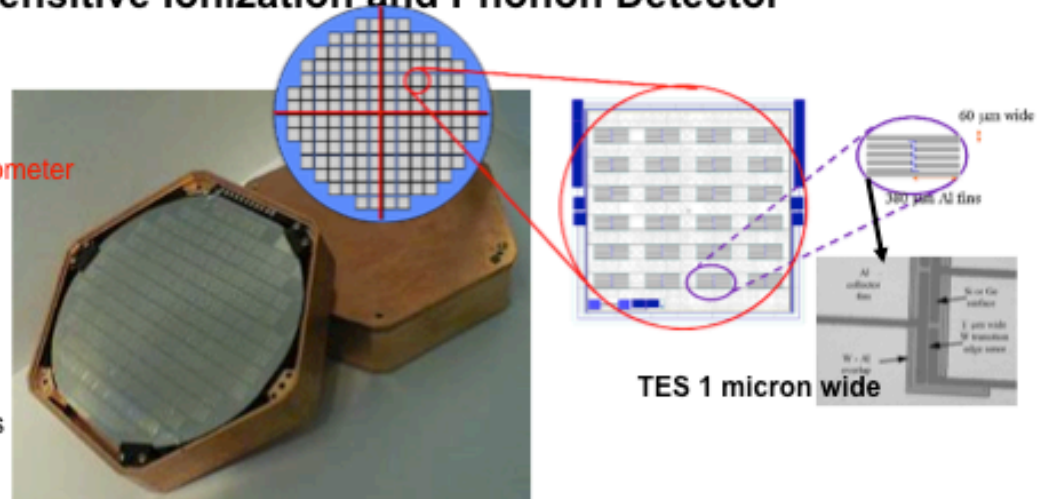


CDMS ZIP detectors

ZIP: Z-sensitive Ionization and Phonon Detector

Detectors :

- 250 g Ge or 100 g Si crystal
- 1 cm thick x 7.5 cm diameter
- Phonon Sensors : Superconducting W thermometer
- Photolithographic patterning
- 4 quadrants
- 37 cells per quadrant
- 6x4 array of 250 μ m x 1 μ m W TES per cell
- Each W sensor "fed" by 8 Al fins
- Ionization Sensors
- 2 electrodes (+ ground) allow rejection of events near outer edge
- Low impedance electronics with Squids
- + FETs pour Ionisation



A. Reisetter, UMinn
PRL 96,011302 (2006)

Physics of phonons degradation :
surface events have faster rise time.

→ 2 parameters used for cuts :

- **Primary risetime** (delay 10% - 40% phonon amp.)

Primary delay delay 20% charge amp and 20% phonon amp.)

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